a dual-terminated transmission line, wherein the dual-terminated transmission line communicatively couples the Direct RAC of first integrated circuit with the Direct RAC of the second integrated circuit.

12. (Once amended) The apparatus of claim 1 [11], wherein impedance of the first metal line is substantially equal to impedance of the second metal line.

15. (Once amended) The apparatus of claim 1 [10], wherein the third integrated circuit comprises a Rambus™ in-line memory module communicatively coupled to the connector.

19. (Once amended) A method of making an article, comprising:

providing a first integrated circuit having a communication module;

providing a connector having a first line and a second line, wherein the first line and the second line are communicatively coupled to the first integrated circuit, and wherein the second line is longer than the first line, has a capacitance value greater than a capacitance value of the first line, and impedance of the second line is approximately equal to impedance of the first line;

providing a second integrated circuit have a communication module; and

forming a dual-terminated transmission line to couple the first integrated circuit to the second integrated circuit.

CLEAN VERSION OF CLAIMS FOR SCANNING PER 37 CFR § 1.121

1. An apparatus comprising:

a first integrated circuit comprising a Direct Rambus™ ASIC Cell (Direct RAC);

a second integrated circuit comprising a Direct RAC;

a mezzanine card having a connector and comprising the second integrated circuit, wherein the connector is adapted to be communicatively coupled to a third integrated circuit, wherein the connector includes a first metal line and a second metal line, the second metal line being longer than the first metal line, and wherein the second metal line has a parasitic capacitance value greater than a parasitic capacitance value of the first metal line; and

a dual-terminated transmission line, wherein the dual-terminated transmission line communicatively couples the Direct RAC of first integrated circuit with the Direct RAC of the second integrated circuit.

10~~12~~. The apparatus of claim 1, wherein impedance of the first metal line is substantially equal to impedance of the second metal line.

13~~15~~. The apparatus of claim 1, wherein the third integrated circuit comprises a Rambus™ in-line memory module communicatively coupled to the connector.

17~~18~~. A method of making an article, comprising:

providing a first integrated circuit having a communication module;

providing a connector having a first line and a second line, wherein the first line and the second line are communicatively coupled to the first integrated circuit,

and wherein the second line is longer than the first line, has a capacitance value greater than a capacitance value of the first line, and impedance of the second line is approximately equal to impedance of the first line;

providing a second integrated circuit have a communication module; and

forming a dual-terminated transmission line to couple the first integrated circuit to the second integrated circuit.